

## AMENDMENTS TO THE CLAIMS

Claim 1. (currently amended) A laminate support used in the process of wire bonding a circuit device comprising:

a substrate having a first surface; and

a wire having a diameter positioned on said first surface of said substrate, said substrate including a closed woven mesh having strands whose separation distance is equal to or less than said diameter of said wire on said first surface of said substrate to substantially prevent deformation of said circuit device during said process of wire bonding.

Claim 2. (original) The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said separation distance is no greater than 0.7 mils.

Claim 3. (original) The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said separation distance is between 0.2 and 0.7 mils.

Claim 4. (previously amended) The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said woven mesh comprises fiberglass.

Claim 5. (previously amended) The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said woven mesh is between approximately 2.5 and 4.0 mils thick.

Claim 6. (original) The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said circuit device is a pad of large scale integrated design.

Claim 7. (currently amended) A laminate support used in the process of wire bonding a circuit device comprising:

a substrate having a first surface; and

a wire having a thickness positioned on said first surface of said substrate, said substrate including a closed woven mesh having warp and weave strands, whose separation distance is equal to or less than the thickness of said wire on said first surface of said substrate, as measured lengthwise through said closed woven mesh to substantially prevent deformation of said circuit device during said process of wire bonding.

Claim 8. (original) The laminate support used in the process of wire bonding a circuit device in accordance with claim 7, wherein said separation distance is equal to or less than 0.7 mils.

Claim 9. (original) The laminate support used in the process of wire bonding a circuit device in accordance with claim 7, wherein said separation distance is between 0.2 and 0.7 mils.

Claim 10. (previously amended) The laminate support used in the process of wire bonding a circuit device in accordance with claim 7, wherein said woven mesh comprises fiberglass.

Claim 11. (previously amended) The laminate support used in the process of wire bonding a circuit device in accordance with claim 7, wherein said woven mesh is between approximately 2.5 and 4.0 mils thick.

Claim 12. (original) The laminate support used in the process of wire bonding a circuit device in accordance with claim 7, wherein said circuit device comprises a pad of large scale integrated design.